## 506648004 05/06/2021 PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:		NEW ASSIGNMENT	NEW ASSIGNMENT					
NATURE OF CONVEYANCE:		ASSIGNMENT	ASSIGNMENT					
CONVEYING PARTY DA	ΤΑ							
		Name	Execution Date					
HSIAO-TSUNG YEN			05/01/2021					
JIAN-YOU CHEN			05/01/2021					
KA-UN CHAN			05/01/2021					
RECEIVING PARTY DATA								
Name:	REALTEK SEMICONDUCTOR CORPORATION							
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City:	HSINCH	HSINCHU						
State/Country:	Taiwan ROC							
Postal Code:	300							
PROPERTY NUMBERS Total: 1								
Property Type		Number	Number					
Application Number: 1731		17313036	3036					
Fax Number:		703)880-7487 the e-mail address first; if that is uns	uccostul it will be cont					
		; if that is unsuccessful, it will be sen						
Phone:	-	703-639-0151						
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•			T, PC INTELLECTUAL PROPERTY ATTORNEYS					
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ATTORNEY DOCKET NUMBER:		16313-357	16313-357					
NAME OF SUBMITTER:		JUSTIN KING	JUSTIN KING					
SIGNATURE:		/Justin King/	/Justin King/					
DATE SIGNED:		05/06/2021	05/06/2021					
Total Attachments: 2								
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## ASSIGNMENT

WHEREAS, I(we), HSIAO-TSUNG YEN, JIAN-YOU CHEN and KA-UN CHAN whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled.

## TRANSFORMER DEVICE

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

United States Design Patent was

 $\square$  executed on:

□ filed on: Serial No.:

	10.		
C established by PC	T International Patent Application No.:	filed:	designating the
United States of America			
issued on	as U.S. Patent No.:		

WHEREAS, **REALTEK SEMICONDUCTOR CORPORATION** whose post office address is **No. 2**, **Innovation Road II**, **Hsinchu Science Park**, **Hsinchu 300**, **Taiwan (R.O.C.)** hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR NAME HSIAO-TSUNG YEN	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor HSTAD - TSUNG YEM	Date of Signature May 1, 2021
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

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ASSIGNOR NAME	Address
JIAN-YOU CHEN	No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor JIAN-YOU CHEN	Date of Signature May 1, 2021
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)
ASSIGNOR NAME	Address
KA-UN CHAN	No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor Ka-UL CHA	Date of Signature May 1, 2021
Name of Witness (optional)	Name of Witness (optional)

Signature of Witness (Optional)

Signature of Witness (optional)